CLAIMS

1. A method for coating of an inner circular surface (7i) of a coating surface (3b) of a carrier wafer (3) with a coating material (9), the method comprising the steps of:

application of the coating material (9) to the inner circular surface (7i) by a first application means (5) and distribution of the coating material (9) by rotating the carrier wafer (3) around an axis (R) of rotation by rotating means (2, 6),

wherein during the distribution of the coating material (9) by a second application means (4) an outer circular ring surface (7a) which surrounds the inner circular surface (7i) is applied with a coating inhibitor which at least inhibits the coating of the outer circular ring surface (7a),

wherein the coating material (9) is an antiadhesion material, and

wherein the coating inhibitor is applied to the outer circular ring surface (7a) prior to the coating material (9), such that the coating material (9) moves away over the coating inhibitor and the outer circular ring surface (7a) is not coated by the coating material.

2. The method of claim 1, wherein the applications of the coating material (9) and the coating inhibitor are controlled by an activation sequence and a deactivation sequence.

3. The method of claim 2, wherein the activation sequence calls for the coating inhibitor to be applied at instants selected from the group consisting of at latest until the coating material is reached, at the same time with the coating material and prior to the coating material.

4. The method of claim 2, wherein the deactivation sequence calls for the coating with the coating material to end before coating with the coating inhibitor.

5. The method as claimed in one of the preceding claims, further comprising a step of controlling application amounts and/or application pressure and/or application speed and/or application angles and/or application instants of the first and/or second application means (4, 5).

6. The method as claimed in one of the preceding claims, further comprising a step of curing the coating material (9) with curing agents.

7. The method as claimed in one of the preceding claims, wherein the second application means (4) comprises at least one line (41) which can be arranged pointing with one outlet end (4e) toward the circular ring surface (7a).

8. The method as claimed in one of the preceding claims, wherein the second application means (4) comprises on each outlet end (4e) a controllable nozzle (4d).

9. The method as claimed in one of the preceding claims, wherein the coating material (9) is applied in the region of the axis (R) of rotation especially concentrically to the carrier wafer (1).

10. The method as claimed in one of the preceding claims, wherein the application of the coating inhibitor at least in one peripheral section (7u) of the outer circular ring surface (7a) takes place in the region of a radially inner edge (7r) of the outer circular ring surface (7a), which is offset in time for application of the coating material (9).